

form it may be applied with a syringe. Alternatively, expanding foam may be utilized as the separator 28.

In one embodiment, the separator 28 and material 26 may be made of the same material. In some embodiments, the 5 material 26 and separator 28 may be integrated. In another embodiment, a temporary separator 28 may be applied to the modules 15 during transport.

In some embodiments, the optical integrator plates 16 may not be utilized, as shown in Figure 4. In such cases, 10 the gap 14 may be filled with the separator 28 covered by the black material 26a, as shown in Figure 5. That is, the separator 28 may form the entire seam from front to back of the display 10. In still another embodiment, the gap 14 may be filled by front and back portions, the front portion 15 formed at least in part by the material 26a and the back portion formed at least in part by the separator 28.

As in the previous embodiment, the material 26a may be selected and configured to closely match the appearance of the black matrix lines 22. Again, the optical 20 characteristics, as well as the spacing between the material 26a and adjacent black matrix lines 22, is such as to make the gap 14 not readily visible. Moreover, the size of the material 26a may be selected to substantially match that of adjacent black matrix lines 22. Thus, a relatively 25 seamless appearance can be achieved through the construction of the material placed in the gap 14.

Similarly, the material 28 beneath the material 26a may be a resilient material as described previously to prevent jostling between adjacent modules 15, such as the modules 15a and 15e.

5 In some embodiments, the material 26a may be integrated with the material 28. Thus, the same material may be used as the material 26a and the separator 28.

In some embodiments, a thermal attachment material (not shown) and heat spreader (not shown) may be attached
10 to the rear of the panels 12. In addition, a driver integrated circuit (not shown) may be attached between the panels 12 and the heat spreader. Electrical interconnects may be made by appropriate connectors or mounting frames in some embodiments.

15 While the present invention has been described with respect to a limited number of embodiments, those skilled in the art will appreciate numerous modifications and variations therefrom. It is intended that the appended claims cover all such modifications and variations as fall
20 within the true spirit and scope of this present invention.

What is claimed is: